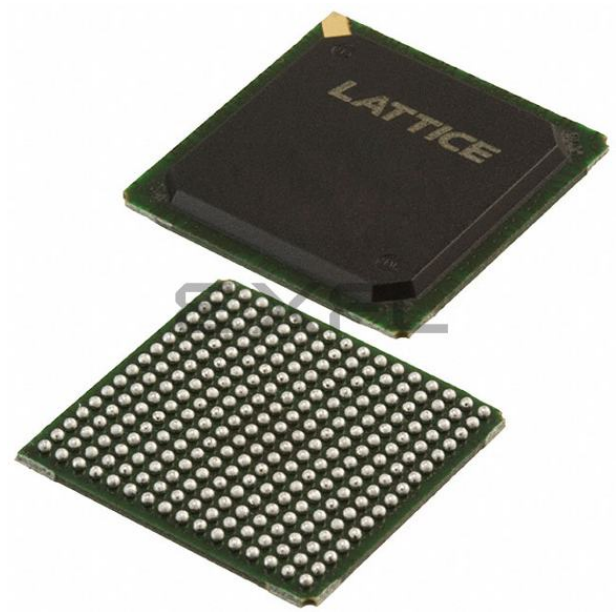
Lattice Semiconductor Corporation - LC5256MV-75F256I Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	256
Number of Gates	-
Number of I/O	141
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5256mv-75f256i

Figure 1. ispXPLD 5000MX Block Diagram

Introduction

The ispXPLD 5000MX family represents a new class of device, referred to as the eXpanded Programmable Logic Devices (XPLDs). These devices extend the capability of Lattice's popular SuperWIDE ispMACH 5000 architecture by providing flexible memory capability. The family supports single- or dual-port SRAM, FIFO, and ternary CAM operation. Extra logic has also been included to allow efficient implementation of arithmetic functions. In addition, sysCLOCK PLLs and sysIO interfaces provide support for the system-level needs of designers.

The devices provide designers with a convenient one-chip solution that provides logic availability at boot-up, design security, and extreme reconfigurability. The use of advanced process technology provides industry-leading performance with combinatorial propagation delay as low as 4.0ns, 2.8ns clock-to-out delay, 2.2ns set-up time, and operating frequency up to 300MHz. This performance is coupled with low static and dynamic power consumption. The ispXPLD 5000MX architecture provides predictable deterministic timing.

The availability of 3.3, 2.5 and 1.8V versions of these devices along with the flexibility of the sysIO interface helps users meet the challenge of today's mixed voltage designs. Inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. Boundary scan testability further eases integration into today's complex systems. A variety of density and package options increase the likelihood of a good fit for a particular application. Table 1 shows the members of the ispXPLD 5000MX family.

Architecture

The ispXPLD 5000MX devices consist of Multi-Function Blocks (MFBs) interconnected with a Global Routing Pool. Signals enter and leave the device via one of four sysIO banks. Figure 1 shows the block diagram of the ispXPLD

Programmable Slew Rate

The slew rate of outputs is carefully controlled. When outputs are configured as LVCMOS the devices support two slew rates. This allows system noise and performance to be balanced in a design.

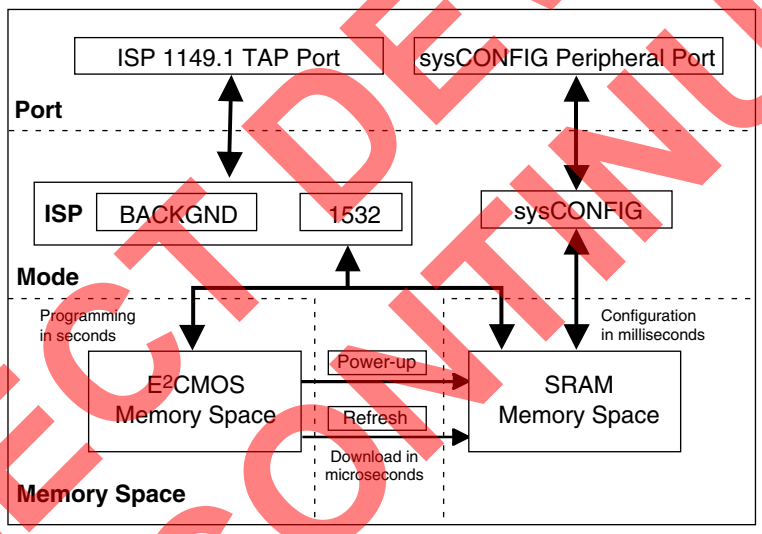
Programmable Bus-Maintenance

All general-purpose inputs have programmable bus maintenance circuitry. These are intended to maintain a valid logic level into a device when driving devices go into the tri-state mode. Four options are available for users: pull-up, pull-down, bus-keeper, or nothing.

Expanded In-System Programmability (ispXP)

The ispXPLD 5000MX family utilizes a combination of EEPROM non-volatile cells and SRAM technology to deliver a logic solution that provides “instant-on” at power-up, a convenient single chip solution, and the capability for infinite reconfiguration. A non-volatile array distributed within the device stores the device configuration. At power-up this information is transferred in a massively parallel fashion into SRAM bits that control the operation of the device. Figure 18 shows the different ports and modes that are used in the configuration and programming of the ispXPLD 5000MX devices.

Figure 18. ispXP Block Diagram



IEEE 1532 ISP

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispXPLD 5000MX devices provide in-system programmability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The IEEE1532 programming interface allows programming of either the non-volatile array or reconfiguration of the SRAM bits.

The ispXPLD 5000MX devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispXPLD 5000MX devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispXPLD 5000MX devices during the testing of a circuit board.

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Absolute Maximum Ratings[1, 2, 3]

	ispXPLD 5000MC 1.8V	ispXPLD 5000MB/V 2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IHMAX} +2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage for 1.8V Devices (ispXPLD 5000MC)	1.65	1.95	V
	Supply Voltage for 2.5V Devices (ispXPLD 5000MB)	2.3	2.7	V
	Supply Voltage for 3.3V Devices (ispXPLD 5000MV)	3	3.6	V
V_{CCP}	PLL Block Supply Voltage for PLL 1.8V Devices	1.65	1.95	V
	PLL Block Supply Voltage for PLL 2.5V Devices	2.3	2.7	V
	PLL Block Supply Voltage for PLL 3.3V Devices	3	3.6	V
T_J	Junction Temperature (Commercial Operation)	0	90	C
	Junction Temperature (Industrial Operation)	-40	105	C

E²CMOS Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO}þð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and $V_{CCO,}$ provided (V_{IN} - V_{CCO})þð 3.6V.
2. 0 ð V_{CC} ð V_{CC} (MAX), 0 ð V_{CCO} ð V_{CCO} (MAX)
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.
4. LVTTL, LVCMOS only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Leakage	0 ð V_{IN} ð (V_{CCO} - 0.2V)	—	—	10	µA
		(V_{CCO} - 0.2V) < V_{IN} ð 3.6V	—	—	40	µA
I_{IH}[4]	Input High Leakage Current	3.6V < V_{IN} ð 5.5V and 3.0V ð V_{CCO} ð 3.6V	—	—	3	mA
I_{PU}[3]	I/O Active Pullup Current	0 ð V_{IN} ð 0.7 V_{CCO}	-30	—	-150	µA
I_{PD}	I/O Active Pulldown Current	V_{IL} (MAX) ð V_{IN} ð V_{IH} (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low Sustaining Current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	V_{IN} = 0.7 V_{CCO}	30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
V_{BHT}	Bus Hold Trip Points	0 ð V_{IN} ð V_{IH} (MAX)	V_{CCO} * 0.35	—	V_{CCO} * 0.65	µA
C1	I/O Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Clock Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3	Global Input Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f=1.0MHz
3. I_{PU} on JTAG pins has a maximum of -175µA for 5512MX devices.
4. 5V tolerant inputs and I/Os should be placed in banks where 3.0V ð V_{CCO} ð 3.6V. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.

sysIO Differential DC Electrical Characteristics

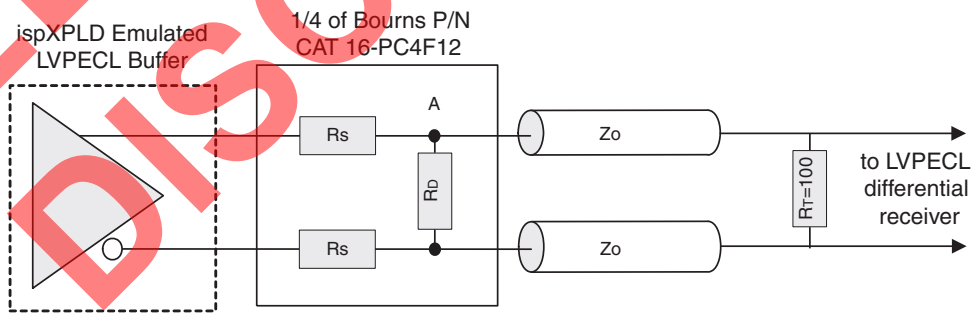
Over Recommended Operating Conditions

Parameter	Description	Test Conditions	Min.	Typ.	Max.
LVDS					
V_{INP}	Input Voltage		0V	—	2.4V
V_{THD}	Differential Input Threshold	0.2 ð V_{CM} ð 1.8V	+/-100mV	—	—
I_{IN}	Input Current	Power On	—	—	+/-10uA
V_{OH}	Output High Voltage for V_{OP} or V_{OM}	RT = 100 Ohm	—	1.38V	1.60V
V_{OL}	Output Low Voltage for V_{OP} or V_{OM}	RT = 100 Ohm	0.9V	1.03V	—
V_{OD}	Output Voltage Differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250mV	350mV	450mV
ΔV_{OD}	Change in V_{OD} Between High and Low		—	—	50mV
V_{OS}	Output Voltage Offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125V	1.20V	1.375V
ΔV_{OS}	Change in V_{OS} Between H and L		—	—	50mV
I_{OSD}	Output Short Circuit Current	V_{OD} = 0V Driver outputs shorted	—	—	24mA

LVPECL[1]								
DC Parameter	**Parameter Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
V_{CCO}		**3.0**		**3.3**		**3.6**		**V**
V_{IH}	Input Voltage High	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	Input Voltage Low	0.86	2.125	0.86	2.125	0.86	2.125	V
V_{OH}	Output Voltage High	1.7	2.11	1.92	2.28	2.03	2.41	V
V_{OL}	Output Voltage Low	0.96	1.27	1.06	1.43	1.3	1.57	V
V_{DIFF}[2]	Differential Input voltage	0.3	—	0.3	—	0.3	—	V

1. These values are valid at the output of the source termination pack as shown above with 100-ohm differential load only (see Figure 19). The V_{OH} levels are 200mV below the standard LVPECL levels and are compatible with devices tolerant of the lower common mode ranges.
2. Valid for 0.2 ð V_{CM} ð 1.8V

Figure 19. LVPECL Driver with Three Resistor Pack



ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{CASC}	Additional Delay for PT Cascading between MFBs	—	—	0.71	—	0.80	—	0.89	—	0.92	—	1.33	ns
$t_{CICOMFB}$	Carry Chain Delay, MFB to MFB	—	—	0.35	—	0.39	—	0.44	—	0.46	—	0.66	ns
t_{CICOMC}	Carry Chain Delay, Macro-Cell to Macro-Cell	—	—	0.10	—	0.11	—	0.13	—	0.13	—	0.19	ns
t_{FLAG}	Routing Delay for Extended Function Flags	—	—	2.62	—	2.94	—	3.27	—	3.40	—	4.91	ns
$t_{FLAGEXP}$	Additional Flag Delay when Expanding Data Widths	$t_{FLAGFULL}$, $t_{FLAGAFULL}$, $t_{FLAGEMPTY}$, $t_{FLAGAEMPTY}$	—	2.57	—	2.89	—	3.21	—	3.34	—	4.82	ns
t_{SUM}	Counter Sum Delay	t_{PTSA}	—	0.80	—	0.90	—	1.00	—	1.04	—	1.50	ns
Optional Adjusters													
t_{BLA}	Block Loading Adder	t_{ROUTE}	—	0.04	—	0.04	—	0.05	—	0.05	—	0.07	ns
t_{EXP}	PT Expander Adder	t_{ROUTE}	—	0.53	—	0.60	—	0.66	—	0.69	—	0.99	ns
t_{INDIO}	Additional Delay for the Input Register	t_{INREG}	—	0.50	—	0.56	—	0.63	—	0.65	—	0.94	ns
$t_{PLL\_SEC\_DELAY}$	Secondary PLL Output Delay	t_{PLL_DELAY}	—	0.91	—	0.91	—	0.91	—	0.91	—	0.91	ns
t_{INEXP}	MFB Input Extender	t_{ROUTE}	—	0.62	—	0.70	—	0.78	—	0.81	—	1.16	ns
Input and Output Buffer Delays													
t_{IOI}	Input Buffer Selection Adder	t_{GCLK_IN}, t_{IN}, t_{GOE}, t_{RST}	Refer to sysIO Adjuster Tables										ns
t_{IOO}	Output Buffer Selection Adder	t_{BUF}											ns
FIFO													
$t_{FIFOWCLKS}$	Write Data Setup before Write Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{FIFOWCLKH}$	Write Data Hold after Write Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{FIFOCLKSKEW}$	Opposite Clock Cycle Delay	—	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	ns
$t_{FIFOFULL}$	Write Clock to Full Flag Delay	—	—	3.08	—	3.08	—	3.85	—	3.85	—	4.00	ns
$t_{FIFOAFULL}$	Write Clock to Almost Full Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
$t_{FIFOEMPTY}$	Read Clock to Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
$t_{FIFOAEMPTY}$	Read Clock to Almost Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{SPADDH}	Address Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{SPRWS}	R/W Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{SPRWH}	R/W Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{SPDATAS}$	Data Setup before Clock Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{SPDATAH}$	Data Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{SPCLKO}	Clock to Output Delay	—	—	5.97	—	5.97	—	5.97	—	5.97	—	9.86	ns
t_{SPRSTO}	Reset to RAM Output Delay	—	—	3.30	—	3.30	—	3.30	—	3.30	—	4.29	ns
t_{SPRSTR}	Reset Recovery Time	—	1.20	—	1.20	—	1.20	—	1.20	—	1.56	—	ns
$t_{SPRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.14	—	0.14	—	0.19	—	ns
Pseudo Dual Port RAM													
t_{PDPMSS}	Memory Select Setup Before Clock	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
t_{PDPMSH}	Memory Select Hold time after Clock	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPRCES}$	Clock Enable Setup before Read Clock Time	—	2.33	—	2.33	—	2.91	—	2.91	—	3.03	—	ns
$t_{PDPRCEH}$	Clock Enable Hold time after Read Clock Time	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns
$t_{PDPWCES}$	Clock Enable Setup before Write Clock Time	—	1.87	—	1.87	—	2.34	—	2.34	—	2.43	—	ns
$t_{PDPWCEH}$	Clock Enable Hold time after Write Clock Time	—	-2.95	—	-2.95	—	-2.36	—	-2.36	—	-2.27	—	ns
$t_{PDPRADDS}$	Read Address Setup before Read Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{PDPRADDH}$	Read Address Hold after Read Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPWADDS}$	Write Address Setup before Write Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{PDPWADDH}$	Write Address Hold after Write Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{PDPRWS}	R/W Setup before Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PDPRWH}	R/W Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPDATAS}$	Data Setup before Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{PDPDATAH}$	Data Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPRCLKO}$	Read Clock to Output Delay	—	—	5.08	—	5.02	—	5.66	—	5.45	—	8.54	ns
$t_{PDPCLKSKEW}$	Opposite Clock Cycle Delay	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	—	ns
$t_{PDPRSTO}$	Reset to RAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{PDPRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{PDPRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
Dual Port RAM													
t_{DPMSAS}	Memory Select A Setup Before R/W A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSAH}	Memory Select Hold time after R/W A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPCEAS}	Clock Enable A Setup before Clock A Time	—	3.72	—	3.72	—	3.72	—	3.72	—	4.84	—	ns
t_{DPCEAH}	Clock Enable A Hold time after Clock A Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
$t_{DPADDAS}$	Address A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPADDAH}$	Address A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPRWAS}	R/W A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPRWAH}	R/W A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{DPDATAAS}$	Write Data A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPDATAAH}$	Write Data A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPMSBS}	Memory Select B Setup Before R/W B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSBH}	Memory Select Hold time after R/W B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Units
t_{PWH}	Input clock, high time	80% to 80%	1.2	—	ns
t_{PWL}	Input clock, low time	20% to 20%	1.2	—	ns
t_R, t_F	Input Clock, rise and fall time	20% to 80%	—	3.0	ns
t_{INSTB}	Input clock stability, cycle to cycle (peak)		—	+/- 250	ps
f_{MDIVIN}	M Divider input, frequency range		10	320	MHz
$f_{MDIVOUT}$	M Divider output, frequency range		10	320	MHz
f_{NDIVIN}	N Divider input, frequency range		10	320	MHz
$f_{NDIVOUT}$	N Divider output, frequency range		10	320	MHz
f_{VDIVIN}	V Divider input, frequency range		100	400	MHz
$f_{VDIVOUT}$	V Divider output, frequency range		10	320	MHz
$t_{OUTDUTY}$	Output clock, duty cycle		40	60	%
$t_{JIT(CC)}$	Output clock, cycle to cycle jitter (peak)	Clean reference. 10 MHz < $f_{MDIVOUT}$ < 20 MHz or 100MHz < f_{VDIVIN} < 160 MHz[1]	—	+/- 250	ps
		Clean reference. 20 MHz < $f_{MDIVOUT}$ < 320 MHz and 160MHz < f_{VDIVIN} < 320 MHz[1]	—	+/- 150	ps
$T_{JIT(PERIOD)}$[2]	Output clock, period jitter (peak)	Clean reference. 10 MHz < $f_{MDIVOUT}$ < 20 MHz or 100MHz < f_{VDIVIN} < 160 MHz[1]	—	+/- 300	ps
		Clean reference. 20 MHz < $f_{MDIVOUT}$ < 320 MHz and 160MHz < f_{VDIVIN} < 320 MHz[1]	—	+/- 150	ps
$t_{CLK\_OUT\_DLY}$	Input clock to CLK_OUT delay	Internal feedback	—	3.0	ns
t_{PHASE}	Input clock to external feedback delta	External feedback	—	600	ps
t_{LOCK}	Time to acquire phase lock after input stable		—	25	us
t_{PLL_DELAY}	Delay increment (Lead/Lag)	Typical = +/- 250ps	+/- 120	+/- 550	ps
t_{RANGE}	Total output delay range (lead/lag)		+/- 0.84	+/- 3.85	ns
t_{PLL_RSTW}	Minimum reset pulse width		—	1.8	ns
t_{CLK_IN}[3]	Global clock input delay		—	1.0	ns
$t_{PLL\_SEC\_DELAY}$	Secondary PLL output delay (t_{PLL_DELAY})		—	1.5	ns

1. This condition assures that the output phase jitter will remain within specification.
2. Accumulated jitter measured over 10,000 waveform samples.
3. Internal timing for reference only.

ispXP sysCONFIG Port Timing Specifications

Symbol	Timing Parameter	Min.	Max.	Units
sysCONFIG Write Cycle Timing				
t_{SUCS}	Input setup time of CS to CCLK rise	10	—	ns
t_{HCS}	Hold time of CS to CCLK rise	1	—	ns
t_{SUWD}	Input setup time of write data to CCLK rise	10	—	ns
t_{HWD}	Hold time of write data to CCLK rise	0	—	ns
t_{PRGM}	Low time to reset device SRAM	5	50	ns
t_{DINIT}	INIT delay time	—	5	ms
t_{IODISS}	User I/O disable	—	—	ns
t_{IOENSS}	User I/O enable	—	—	ns
t_{WH}	Write clock High pulse width	18	—	ns
t_{WL}	Write clock Low pulse width	18	—	ns
f_{MAXW}	Write f_{MAX}	—	27	MHz
sysCONFIG Read Cycle Timing				
t_{HREAD}	Hold time of READ to CCLK rise	1	—	ns
t_{SUREAD}	Input setup time of READ High to CCLK rise	15	—	ns
t_{RH}	READ clock high pulse width	18	—	ns
t_{RL}	READ clock low pulse width	18	—	ns
f_{MAXR}	Read f_{MAX}	—	27	MHz
t_{CORD}	Clock to out for read data	—	25	ns

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
2	20P	C14	-	-	C15	P11
2	20N	C16/VREF2	-	-	C17	T14
2	21P	C18	C8	D8	C19	R12
2	21N	C20	C9	D9	-	R13
2	22P	C21	C10	D10	-	N11
2	22N	C22	C11	D11	C23	T15
2	23P	C24	C12	D12	C25	R14
2	23N	C26	C13	D13	C27	N12
2	24P	C28	C14	D14	C29	P12
2	24N	C30	C15	D15	C31	R15
-	-	VCCO2	-	-	-	VCCO2
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)
2	25P	D0	-	-	D1	N15
2	25N	D2	-	-	D3	N14
2	26P	D4	C16	D16	-	N16
2	26N	D5	C17	D17	-	M16
2	27P	D6	C18	D18	D7	M14
2	27N	D8	C19	D19	D9	M15
-	-	VCC	-	-	-	VCC
2	28P	D10	C20	D20	D11	L13
2	28N	D12	C21	D21	D13	L12
2	29P	D14	C22	D22	D15	L15
2	29N	D16	C23	D23	D17	L16
-	-	GND	-	-	-	GND
2	30P	D18	C24	D24	D19	L14
-	-	VCCO2	-	-	-	VCCO2
2	30N	D20	C25	D25	-	K15
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)
2	31P	D21	C26	D26	-	K14
2	31N	D22	C27	D27	D23	K12
2	32P	D24	C28	D28	D25	K13
2	32N	D26	C29	D29	D27	J13
2	33P	D28	C30	D30	D29	J14
2	33N	D30	C31	D31	D31	J12
-	-	TOE	-	-	-	J15
-	-	RESET	-	-	-	J11
-	-	GOE0	-	-	-	H11
-	-	GOE1	-	-	-	H13
-	-	GNDP	-	-	-	See Power Supply and NC Connections Table
-	GCLK3N	GCLK2	-	-	-	H15
-	-	VCCP	-	-	-	See Power Supply and NC Connections Table
-	GCLK3P	GCLK3	-	-	-	H16

ispXPLD 5512MX Logic Signal Connections

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
0	109N	O30	O11	P18	O31	208	C4	B4
0	109P	O28	O10	P16	O29	1	E4	A4
0	110N	O26	M17	O17	O27	2	B1	B3
0	110P	O24	M16	O16	O25	3	C1	A3
0	111N	O22	M15	O15	O23	4	D3	F5
—	—	V_{CCO0}	—	—	—	5	V_{CCO0}	V_{CCO0}
0	111P	O20	M14	O14	O21	6	C2	G6
—	—	GND (Bank 0)	—	—	—	7	GND (Bank 0)	GND (Bank 0)
0	112N	O18	M13	O13	O19	8	E3	H6
0	112P	O16	M12	O12	O17	9	D2	G5
0	113N	O14	O9	P14	O15	—	—	D3
0	113P	O12	O8	P12	O13	—	—	D2
0	114N	O10	O7	P10	O11	—	—	E4
0	114P	O8	O6	P8	O9	—	—	E3
0	115N	O6	O5	P6	O7	—	—	F4
0	115P	O4	O4	P4	O5	—	—	G4
0	116N	O2	O3	P2	O3	—	—	C2
—	—	V_{CCO0}	—	—	—	—	V_{CCO0}	V_{CCO0}
0	116P	O0	O2	P0	O1	—	—	C1
—	—	GND (Bank 0)	—	—	—	—	GND (Bank 0)	GND (Bank 0)
0	117N	P30	O1	—	P31	—	D1	F3
0	117P	P28	O0	—	P29	—	E1	G3
0	118N	P26	O31	—	P27	—	F4	H4
—	—	V_{CC}	—	—	—	10	V_{CC}	V_{CC}
0	118P	P24	O30	—	P25	—	F5	J4
0	119N	P22	M11	O11	P23	11	E2	H5
0	119P	P20/CLK_OUT0	M10	O10	P21	12	F2	J5
0	120N	P18	M9	O9	P19	13	F1	E2
0	120P	P16	M8	O8	P17	14	G1	F2
—	—	GND	—	—	—	15	GND	GND
0	121N	P14	M7	O7	P15	16	F3	D1
—	—	V_{CCO0}	—	—	—	17	V_{CCO0}	V_{CCO0}
0	121P	P12	M6	O6	P13	18	G5	E1
—	—	GND (Bank 0)	—	—	—	19	GND (Bank 0)	GND (Bank 0)
0	122N	P10	M5	O5	P11	20	H5	J3
0	122P	P8/PLL_RST0	M4	O4	P9	21	G4	H2
0	123N	P6	—	—	P7	22	G3	G2
0	123P	P4/PLL_FBK0	—	—	P5	23	H3	G1
0	124N	P2	—	—	P3	24	G2	H1
0	124P	P0	—	—	P1	25	H1	J1
—	GCLK0P	GCLK0	—	—	—	26	H2	N7
—	—	V_{CCJ}	—	—	—	See Power Supply and NC Connections Table		

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
2	47N	G26	—	—	G27	108	N14	V19
—	—	GND (Bank 2)	—	—	—	109	GND (Bank 2)	GND (Bank 2)
2	48P	G28	F16	H16	G29	110	N16	T18
2	48N	G30	F17	H17	G31	111	M16	R17
2	49P	H0	F18	H18	H1	112	M14	U19
2	49N	H2	F19	H19	H3	113	M15	T19
2	50P	H4	E24	—	H5	—	—	V20
—	—	V_{CC}	—	—	—	114	VCC	VCC
2	50N	H6	E26	—	H7	—	NC	U20
2	51P	H8	F20	H20	H9	115	L13	W20
2	51N	H10	F21	H21	H11	116	L12	Y21
2	52P	H12	F22	H22	H13	117	L15	R18
2	52N	H14	F23	H23	H15	118	L16	R19
—	—	GND	—	—	—	119	GND	GND
2	53P	H16	F24	H24	H17	120	L14	W21
—	—	V_{CCO2}	—	—	—	121	V_{CCO2}	V_{CCO2}
2	53N	H18	F25	H25	H19	122	K15	Y22
—	—	GND (Bank 2)	—	—	—	123	GND (Bank 2)	GND (Bank 2)
2	54P	H20	F26	H26	H21	124	K14	R20
2	54N	H22	F27	H27	H23	125	K12	P20
2	55P	H24	F28	H28	H25	126	K13	T21
2	55N	H26	F29	H29	H27	127	J13	R21
2	56P	H28	F30	H30	H29	128	J14	U21
2	56N	H30	F31	H31	H31	129	J12	V21
—	—	TOE	—	—	—	130	J15	W22
—	—	RESET	—	—	—	131	J11	V22
—	—	GOE0	—	—	—	132	H11	T22
—	—	GOE1	—	—	—	133	H13	R22
—	—	GNDP	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3N	GCLK2	—	—	—	135	H15	P16
—	—	V_{CCP}	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3P	GCLK3	—	—	—	137	H16	N16
3	57N	I30	—	—	I31	138	H14	J22
3	57P	I28	—	—	I29	139	G16	H22
3	58N	I26	—	—	I27	140	G15	E22
3	58P	I24/PLL_FBK1	—	—	I25	141	F15	E21
3	59N	I22/PLL_RST1	I27	K27	I23	142	H12	G22
3	59P	I20	I26	K26	I21	143	G14	F21
—	—	GND (Bank 3)	—	—	—	144	GND (Bank 3)	GND (Bank 3)
3	60N	I18	I25	K25	I19	145	F16	H21
—	—	VCCO3	—	—	—	146	V_{CCO3}	V_{CCO3}
3	60P	I16	I24	K24	I17	147	E16	G21
—	—	GND	—	—	—	148	GND	GND

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	143N	U22	U27	W27	U23	—	K6
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	143P	U20	U26	W26	U21	—	K3
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	144N	U18	U25	W25	U19	—	K5
0	144P	U16	U24	W24	U17	—	K2
0	145N	U14	U23	W23	U15	—	L5
0	145P	U12	U22	W22	U13	—	K1
0	146N	U10	U21	W21	U11	—	L6
0	146P	U8	U20	W20	U9	—	L1
0	147N	U6	U19	W19	U7	—	M5
0	147P	U4	U18	W18	U5	—	L2
0	148N	U2	U17	W17	U3	—	N5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	148P	U0	U16	W16	U1	—	L3
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	149N	W30	U15	W15	W31	—	M6
0	149P	W28	U14	W14	W29	—	M2
0	150N	W26	U13	W13	W27	—	P5
-	-	VCC	-	-	-	VCC	VCC
0	150P	W24	U12	W12	W25	—	P6
0	151N	W22	U11	W11	W23	—	M3
0	151P	W20	U10	W10	W21	—	N6
0	152N	W18	U9	W9	W19	—	N2
0	152P	W16	U8	W8	W17	—	P1
-	-	GND	-	-	-	GND	GND
0	153N	W14	U7	W7	W15	—	N3
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	153P	W12	U6	W6	W13	—	M8
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	154N	W10	U5	W5	W11	—	N8
0	154P	W8	U4	W4	-	—	P2
0	155N	W6	U3	W3	W7	—	P8
0	155P	W4	U2	W2	W5	—	N4
0	156N	W2	U1	W1	W3	G2	H1
0	156P	W0	U0	W0	W1	H1	J1
-	GCLK0P	GCLK0	-	-	-	H2	N7
-	-	VCCJ	-	-	-	See Power Supply and NC Connections Table	
-	GCLK0N	GCLK1	-	-	-	J2	P7
-	-	GND	-	-	-	GND	GND
-	-	TDI	-	-	-	H6	R1
-	-	TMS	-	-	-	H4	R2

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	-	C28	D14	-	C29	P5	U8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	15P	C26	D16	-	C27	T4	V6
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	15N	C24	D18	-	C25	T5	V7
-	-	GND	-	-	-	GND	GND
1	16P	C22	D20	-	C23	R4	Y5
-	-	VCC	-	-	-	VCC	VCC
1	16N	C20	D22	-	C21	N6	AA5
1	17P	C18	-	-	C19	R5	Y6
1	17N	C16	-	-	C17	P6	Y7
1	18P	C14	-	-	C15	—	AA6
1	18N	C12	-	-	C13	—	AA7
1	19P	C10	-	-	C11	—	W7
1	19N	C8	-	-	C9	M7	V8
1	20P	C6	-	-	C7	T6	W8
1	20N	C4	-	-	C5	R6	U9
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	L8	U10
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	21P	C0	C16	A16	C1	T7	AB7
1	21N	D30	C17	A17	D31	R7	AA8
1	22P	D28	C18	A18	D29	N7	AB8
1	22N	D26	C19	A19	D27	P7	AB9
1	23P	D24	C20	A20	D25	T8	W9
1	23N	D22	C21	A21	D23	R8	Y9
1	24P	D20	C22	A22	D21	M8	AB10
1	24N	D18	C23	A23	D19	P8	AA10
1	-	D16/VREF1	-	-	D17	L9	W10
1	25P	D14	C24	A24	D15	N8	Y10
1	25N	D12	C25	A25	D13	M9	Y11
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	26P	D10	C26	A26	D11	N10	V9
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	26N	D8	C27	A27	D9	T9	V10
1	27P	D6	C28	A28	D7	T10	AA11
-	-	GND	-	-	-	GND	GND
1	27N	D4	C29	A29	D5	R9	AB11
-	-	VCC	-	-	-	VCC	VCC
1	28P	D2	C30	A30	D3	P9	U11
1	28N	D0	C31	A31	D1	N9	V11
2	29P	E0	F0	H0	E1	T11	AB12
-	-	VCC	-	-	-	VCC	VCC

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	15N	C0	A31	C31	C1	—	W5
1	16P	E30/DATA0	G0	E0	E31	W1	W1
1	16N	E28/DATA1	G1	E1	E29	Y1	Y1
1	17P	E26/DATA2	G2	E2	E27	P3	V6
1	17N	E24/DATA3	G3	E3	E25	R3	W6
1	18P	E22/DATA4	G4	E4	E23	T2	Y2
1	18N	E20/DATA5	G5	E5	E21	U2	Y3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	19P	E18/DATA6	G6	E6	E19	V2	Y4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	19N	E16/DATA7	G7	E7	E17	W2	Y5
-	-	GND	-	-	-	GND	GND
1	20P	E14/INITB	G8	E8	E15	R4	V7
1	20N	E12/CSB	G9	E9	E13	T4	W7
1	21P	E10/READ	G10	E10	E11	R6	AA1
1	21N	E8/CCLK	G11	E11	E9	R5	AA2
1	22P	E6	-	-	E7	U3	AA3
-	-	VCC	-	-	-	VCC	VCC
1	22N	E4	-	-	E5	V3	AA4
1	23P	E2	-	-	E3	Y2	Y6
1	23N	E0	-	-	E1	W3	AA5
1	24P	F30	H0	-	F31	U5	AB2
1	24N	F28	H2	-	F29	T5	AB3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	25P	F26	H4		F27	U4	AB4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	25N	F24	H6	-	F25	V4	AB5
1	26P	F22	H8	-	F23	AA3	AB1
1	26N	F20	H10	-	F21	AB3	AC2
1	-	F18	H12	-	F19	Y4	AC3
-	-	DONE	-	-	-	AA4	AC4
1	27P	F14	-	-	F15	AB2	AC1
1	27N	F12	-	-	F13	U6	AD1
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	28P	F10			F11	V5	AD2
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	28N	F8			F9	W6	AD3
1	29P	F6	G12	E12	F7	AB4	Y8
1	29N	F4	G13	E13	F5	AB5	Y9
1	30P	F2	G14	E14	F3	T6	AA8
1	30N	F0	G15	E15	F1	U7	AA9
-	-	PROGRAMB	-	-	-	W5	AB8
1	-	G28	H14	-	G29	U8	AB9

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	63P	K8	L20	-	K9	AA19	AA18
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	63N	K10	L21	-	K11	U17	Y18
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	64P	K12	L22	-	K13	V18	AD25
2	64N	K14	L23	-	K15	AB21	AD26
2	65P	K16	L24	-	K17	U18	AC23
2	65N	K18	L25	-	K19	T17	AC24
2	66P	K20	L26	-	K21	AB20	AC25
2	66N	K22	L27	-	K23	AA20	AC26
2	67P	K24	L28	-	K25	Y19	AB22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	67N	K26	L29	-	K27	V19	AB23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	68P	K28	J16	L16	K29	T18	AB24
2	68N	K30	J17	L17	K31	R17	AB25
2	69P	L0	J18	L18	L1	U19	AB26
2	69N	L2	J19	L19	L3	T19	AA26
2	70P	L4	L30	I24	L5	V20	AA22
-	-	VCC	-	-	-	VCC	VCC
2	70N	L6	L31	I26	L7	U20	Y21
2	71P	L8	J20	L20	L9	W20	AA23
2	71N	L10	J21	L21	L11	Y21	AA24
2	72P	L12	J22	L22	L13	R18	AA25
2	72N	L14	J23	L23	L15	R19	Y26
-	-	GND	-	-	-	GND	GND
2	73P	L16	J24	L24	L17	W21	Y22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	73N	L18	J25	L25	L19	Y22	Y23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	74P	L20	J26	L26	L21	R20	W20
2	74N	L22	J27	L27	L23	P20	V20
2	75P	L24	J28	L28	L25	T21	W21
2	75N	L26	J29	L29	L27	R21	V21
2	76P	L28	J30	L30	L29	U21	Y24
2	76N	L30	J31	L31	L31	V21	Y25
2	77P	N0	P0	N0	N1	—	W22
2	77N	N2	P1	N1	N3	—	W23
2	78P	N4	P2	N2	N5	—	W24
-	-	VCC	-	-	-	VCC	VCC
2	78N	N6	P3	N3	N7	—	W25
-	-	GND	-	-	-	GND	GND
2	79P	N8	P4	N4	N9	—	W26

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	GCLK3P	GCLK3	-	-	-	N16	N24
3	93N	R0	T31	R31	R1	J22	N23
3	93P	R2	T30	R30	R3	H22	N22
3	94N	R4	T29	R29	R5	N19	M26
3	94P	R6	T28	R28	R7	P15	M25
3	95N	R8	T27	R27	R9	P21	M23
3	95P	R10	T26	R26	R11	N15	M22
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	96N	R12	T25	R25	R13	M15	N20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	96P	R14	T24	R24	R15	N20	M20
-	-	GND	-	-	-	GND	GND
3	97N	R16	T23	R23	R17	P22	N21
3	97P	R18	T22	R22	R19	N21	M21
3	98N	R20	T21	R21	R21	N17	M24
3	98P	R22	T20	R20	R23	M20	L24
3	99N	R24	T19	R19	R25	P17	L23
-	-	VCC	-	-	-	VCC	VCC
3	99P	R26	T18	R18	R27	P18	L22
3	100N	R28	T17	R17	R29	M21	L25
3	100P	R30	T16	R16	R31	M17	K26
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	101N	T0	T15	R15	T1	L20	K25
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	101P	T2	T14	R14	T3	N18	K24
3	102N	T4	T13	R13	T5	L21	K23
3	102P	T6	T12	R12	T7	M18	K22
3	103N	T8	T11	R11	T9	L22	J25
3	103P	T10	T10	R10	T11	L17	J24
3	104N	T12	T9	R9	T13	K22	L21
3	104P	T14	T8	R8	T15	L18	K21
3	105N	T16	T7	R7	T17	K21	L20
3	105P	T18	T6	R6	T19	K18	K20
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	106N	T20	T5	R5	T21	K20	J23
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	106P	T22	T4	R4	T23	K17	J22
3	107N	T24	T3	R3	T25	K19	J26
3	107P	T26	T2	R2	T27	J17	H26
3	108N	T28	T1	R1	T29	E22	H25
3	108P	T30/PLL_FBK1	T0	R0	T31	E21	H24
3	109N	U0/PLL_RST1	X27	V27	U1	G22	H23
3	109P	U2	X26	V26	U3	F21	H22

ispXPLD 5000MC (1.8V) Commercial Devices (Continued)

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5768MC	LC5768MC-5F256C	768	1.8	5.0	fpBGA	256	193	C
	LC5768MC-75F256C	768	1.8	7.5	fpBGA	256	193	C
	LC5768MC-5F484C	768	1.8	5.0	fpBGA	484	317	C
	LC5768MC-75F484C	768	1.8	7.5	fpBGA	484	317	C
LC51024MC	LC51024MC-52F484C	1024	1.8	5.2	fpBGA	484	317	C
	LC51024MC-75F484C	1024	1.8	7.5	fpBGA	484	317	C
	LC51024MC-52F672C	1024	1.8	5.2	fpBGA	672	381	C
	LC51024MC-75F672C	1024	1.8	7.5	fpBGA	672	381	C

ispXPLD 5000MC (1.8V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-5F256I	256	1.8	5.0	fpBGA	256	141	I
	LC5256MC-75F256I	256	1.8	7.5	fpBGA	256	141	I
LC5512MC	LC5512MC-75Q208I	512	1.8	7.5	PQFP	208	149	I
	LC5512MC-75F256I	512	1.8	7.5	fpBGA	256	193	I
	LC5512MC-75F484I	512	1.8	7.5	fpBGA	484	253	I
LC5768MC	LC5768MC-75F256I	768	1.8	7.5	fpBGA	256	193	I
	LC5768MC-75F484I	768	1.8	7.5	fpBGA	484	317	I
LC51024MC	LC51024MC-75F484I	1024	1.8	7.5	fpBGA	484	317	I
	LC51024MC-75F672I	1024	1.8	7.5	fpBGA	672	381	I

ispXPLD 5000MB (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-4F256C	256	2.5	4.0	fpBGA	256	141	C
	LC5256MB-5F256C	256	2.5	5.0	fpBGA	256	141	C
	LC5256MB-75F256C	256	2.5	7.5	fpBGA	256	141	C
LC5512MB	LC5512MB-45Q208C	512	2.5	4.5	PQFP	208	149	C
	LC5512MB-75Q208C	512	2.5	7.5	PQFP	208	149	C
	LC5512MB-45F256C	512	2.5	4.5	fpBGA	256	193	C
	LC5512MB-75F256C	512	2.5	7.5	fpBGA	256	193	C
	LC5512MB-45F484C	512	2.5	4.5	fpBGA	484	253	C
	LC5512MB-75F484C	512	2.5	7.5	fpBGA	484	253	C
LC5768MB	LC5768MB-5F256C	768	2.5	5.0	fpBGA	256	193	C
	LC5768MB-75F256C	768	2.5	7.5	fpBGA	256	193	C
	LC5768MB-5F484C	768	2.5	5.0	fpBGA	484	317	C
	LC5768MB-75F484C	768	2.5	7.5	fpBGA	484	317	C
LC51024MB	LC51024MB-52F484C	1024	2.5	5.2	fpBGA	484	317	C
	LC51024MB-75F484C	1024	2.5	7.5	fpBGA	484	317	C
	LC51024MB-52F672C	1024	2.5	5.2	fpBGA	672	381	C
	LC51024MB-75F672C	1024	2.5	7.5	fpBGA	672	381	C